

WASHING LIQUID FOR SEMICONDUCTOR SUBSTRATE AND METHOD OF
PRODUCING SEMICONDUCTOR DEVICE

Abstract

An object of the present invention is to provide washing liquid for semiconductor substrate capable of removing grinding grains of silica, alumina or the like in a polishing agent and polishing trashes of copper, and capable of leaving little organic substance due to an additive used for preventing corrosion of copper on the surface of a copper wiring after washing, while corrosion of copper is suppressed, and a method of producing a semiconductor device using this washing liquid. The object is achieved by washing liquid for a semiconductor substrate having a copper wiring, comprising a basic compound and at least one selected from the group consisting of sugar alcohols and saccharides. Also the present invention provides a method of producing a semiconductor device comprising a step of forming a copper wiring by chemical mechanical polishing and washing it with washing liquid for a semiconductor substrate containing a basic compound and at least one selected from the group consisting of sugar alcohols and saccharides.